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Text of the abstract

The present invention relates to a device and a method for bonding a first substrate with a second substrate, comprising a measuring means configured to detect a percentage amount of a bonded surface of the first and second substrates with respect to a non-bonded surface of the first and second substrates during contact of the first and second substrates; and monitor an advance of a bonding wave between the first and second substrates via the detected percentage amount to enable control of the bonding wave.